

Title (en)  
SEMICONDUCTOR DEVICE

Title (de)  
HALBLEITERBAUELEMENT

Title (fr)  
DISPOSITIF À SEMI-CONDUCTEUR

Publication  
**EP 3336888 B1 20200506 (EN)**

Application  
**EP 16846286 A 20160902**

Priority  
• JP 2015180864 A 20150914  
• JP 2016075851 W 20160902

Abstract (en)  
[origin: EP3336888A1] This semiconductor device has a plurality of external terminals arranged in an array on a bottom surface of a package. The plurality of external terminals include a first external terminal group for receiving an input of a current from outside the device, and a second external terminal group for outputting a current to the outside of the device. The first external terminal group and the second external terminal group are laid out such that respective arrangement patterns thereof are interlocked with each other. The arrangement patterns may be comb-tooth shaped, cross-shaped, S-shaped, T-shaped, L-shaped, or may have a shape comprising a combination thereof. The plurality of external terminals may be pins, solder balls, or electrode pads.

IPC 8 full level  
**H01L 23/12** (2006.01); **H01L 21/60** (2006.01); **H01L 23/498** (2006.01); **H01L 23/528** (2006.01)

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DOCDB simple family (publication)  
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